12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250919000.1
Qualification of TIEM as an additional Assembly site for select devices
Change Notification / Sample Request

Date: September 19, 2025

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250919000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLV271CDBVR	
TPS3813J25DBVR	
TLV61046ADBVR	
LP2985-33DBVR	
SN74LVC1G66DBVR	
TPS3813K33DBVT	
LP2981-50DBVR	
TLV9061SIDBVR	
TPS560430YDBVR	
TL331KDBVR	
TPS3808G09DBVR	
TPS3808G18DBVR	
TPS3813I50DBVR	
LP2985-30DBVR	
TL331IDBVR	
TL331KDBVR	
LMR50410XDBVR	
LP2981A-50DBVR	
TPS7B91033DBVR	
TPS22918DBVR	
LP2985A-33DBVR	
SN74LVC1G66DBVR	
TLV77318PDBVR	
TPS3813I50DBVR	
TPD4E001DBVR	
TPS22929DDBVR	
TPS3813J25DBVT	
TPS560430XFDBVR	
LP2985A-33DBVRM3	
LP2985AIM5X-3.3/NOPB	
LP2985A-25DBVR	
TPS3808G30DBVR	
TLV61046ADBVR	
TPS3813K33DBVR	
TPS22917DBVR	
TPS3808G01DBVR	
TPS3808G18DBVR	
TPS3808G30DBVR	
LP2985AIM5X-3.3/NOPB	
TPS22918DBVR	
TPS3813I50DBVT	
LP2985A-25DBVR	
TPS3813K33DBVT	
LP2981A-50DBVR	
TLV77325PDBVR	
LP2985-33DBVR	
LP2985A-50DBVR	
TPS3808G01DBVR	

LMR54410DBVR	
TLV271CDBVR	
LMR51610XDBVR	
SN74LVC1G3157DBVR	
TPS3808G33DBVR	
LMR54406DBVR	
LP2981-50DBVR	
LP2985-50DBVR	
TPS560430X3FDBVR	
TPS3813J25DBVR	
TPS7B91050DBVR	
TPS3813L30DBVR	
LP2985-33DBVR	
TPS560430XFDBVR	
LP2985A-50DBVR	
LP2985A-50DBVRM3	
TLV2471IDBVR	
TPS560430XDBVR	
TLV2221IDBVR	
TLV9061SIDBVR	
TL331IDBVR	
TLV61070ADBVR	
TPS22929DDBVR	
LP2985A-25DBVRM3	
TPS3813K33DBVR	
TPS3808G33DBVR	
LP2985-50DBVR	
LP2985A-33DBVR	
LMR51610XDBVR	
TPD4E001DBVR	
SN74AHC1G14DBVR	
TPS3808G01DBVR	
TPS3808G09DBVR	
SN74LVC1G3157DBVR	
LP2985-33DBVR	
OPA994IDBVR	
TPS22917DBVR	
LMR50410XDBVR	
TPS3813L30DBVR	
LP2985-18DBVR	
SN74AHC1G14DBVR	
TLV2471IDBVR	
TLV77333PDBVR	

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250919000.1	**PCN Date:**	September 19, 2025
Title:	Qualification of TIEM as an additional Assembly site for select devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	December 18, 2025	**Sample requests accepted until:**	November 18, 2025*

*Sample requests received after November 18, 2025 will not be supported.

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TIEM as an additional Assembly & Test site for select devices. Material differences between assembly sites as follows.

	Current Site	Additional Site
Assembly site	CDAT, PHI	TIEM
Lead finish	NiPdAu/Matte Sn	Matte Sn

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
CDAT	CDA	CHN	Chengdu
PHI	PHI	PHL	Baguio City
TIEM	**CU6**	**MYS**	**Melaka**

Sample Product Shipping Label (not actual product label)

Product Affected:

SN74AHC1G14DBVR	TPS7B91050DBVR	TL331KDBVR
SN74LVC1G3157DBVR	LMR50410XDBVR	TLV2471IDBVR
SN74LVC1G66DBVR	LMR51610XDBVR	TLV271CDBVR
TLV2221IDBVR	LMR54406DBVR	TLV61046ADBVR
TLV77312PDBVR	LMR54410DBVR	TLV61070ADBVR
TLV77318PDBVR	LP2981-50DBVR	TPD4E001DBVR
TLV77325PDBVR	LP2981A-50DBVR	TPS22917DBVR
TLV77333PDBVR	LP2985-18DBVR	TPS22918DBVR
TLV9061SIDBVR	LP2985-30DBVR	TPS22929DDBVR
TPS3813I50DBVR	LP2985-33DBVR	TPS3808G01DBVR
TPS3813I50DBVT	LP2985-50DBVR	TPS3808G09DBVR
TPS3813J25DBVR	LP2985A-25DBVR	TPS3808G18DBVR
TPS3813J25DBVT	LP2985A-25DBVRM3	TPS3808G30DBVR
TPS3813K33DBVR	LP2985A-33DBVR	TPS3808G33DBVR
TPS3813K33DBVT	LP2985A-33DBVRM3	TPS560430X3FDBVR
TPS3813L30DBVR	LP2985A-50DBVR	TPS560430XDBVR
TPS3813L30DBVT	LP2985A-50DBVRM3	TPS560430XFDBVR
TPS79330DBVRM3	LP2985AIM5X-3.3/NOPB	TPS560430YDBVR
TPS79333DBVRM3	OPA994IDBVR	
TPS7B91033DBVR	TL331IDBVR	

Qualification Report

Approve Date 18-FEBRUARY -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LP2980IM5-3.3/NOPB	Qual Device: LM7301IM5X/NOPB	QBS Reference: TLV8811DBVR	QBS Reference: LMP7717MFX/NOPB	QBS Reference: LP5907MFX-1.8/NOPB
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/231/0	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device LP2980IM5-3.3/NOPB is qualified at MSL1 260C
Qual Device LM7301IM5X/NOPB is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2501-067

Qualification Report

Approve Date 06-March-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLV8811DBVR	Qual Device: LMP7717MFX/NOPB	Qual Device: LP5907MFX-1.8/NOPB	QBS Reference: TPS3840PH30DBVRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	3/90/0

QBS: Qual By Similarity
Qual Device TLV8811DBVR is qualified at MSL1 260C
Qual Device LMP7717MFX/NOPB is qualified at MSL1 260C
Qual Device LP5907MFX-1.8/NOPB is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2302-059

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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